

Amendments to the Specification:

Please amend the paragraph beginning at line 11 of page 2 and ending at line 21 of page 2 as follows:

To facilitate the deposition process, the surface of the wafer 10 must have an electrically conducting coating before being immersed in the electrolyte bath 14, and electrical contact must be made with the wafer 10 (to complete the circuit) before deposition can take place. As shown in Figure 1, to facilitate electrical contact with the wafer 10, a contact ring 20 is typically used, where the contact ring 20 includes a top portion 21 and a bottom portion 23, and the top portion includes electrical connectors or contacts 22. The wafer 10 is placed in the contact ring 20 and a backing plate (not specifically shown in Figure 1) is used to apply pressure, causing the electrical contacts 22 of the top portion 21 of the contact ring 20 to electrically contact the electrically conducting coating on the wafer 10. Thereafter, an electrical potential is applied, resulting in the formation of a layer of copper (of desired thickness) on the wafer 10.

Please amend the paragraph beginning at line 13 of page 9 and ending at line 3 of page 10 as follows:

As shown in Figure 2, the device 30 includes a substrate 32 (i.e., a wafer), which can be a silicon substrate, a metal substrate fabricated to accomplish the desired measurements, or a substrate formed of some other, suitable material. A conductive pattern 34 (such as a copper pattern, or some other highly conductive film) is etched or otherwise provided on the substrate 32, preferably in the shape of electrical contacts 22 on the top portion 21 of a contact ring 20 (see

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Figures 1 and 4). Preferably, the conductive pattern 34 terminates with wires 36 attached to the wafer 32 leading to a connector. More specifically, preferably the conductive pattern 34 is connected to resistance measurement circuitry 38, where the resistance measurement circuitry 38 is configured to send test signals to the conductive pattern 34, receive signals from the conductive pattern 34, and measure the resistances associated with the electrical contacts 22 of top portion 21 of the contact ring 20.

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